ABSTRACT

The invention relates to a semiconductor device formed by using a film carrier tape and having a package size that is close to the chip size, and also to a semiconductor device and a making method therefor which facilitates the injection of resin for sealing. A film carrier tape 32 comprises a plurality of connection leads (24); portions defining holes (29, 31) formed by punching out connection portions, where any one of the connection leads (24) are connected together, and by punching out an intersection portion; and portions defining rectangular holes (11, 15). Resin is injected through rectangular holes (11, 15), rectangular holes (12, 14) stop the spreading of the resin, and holes (29, 31) allow air to escape from the resin.